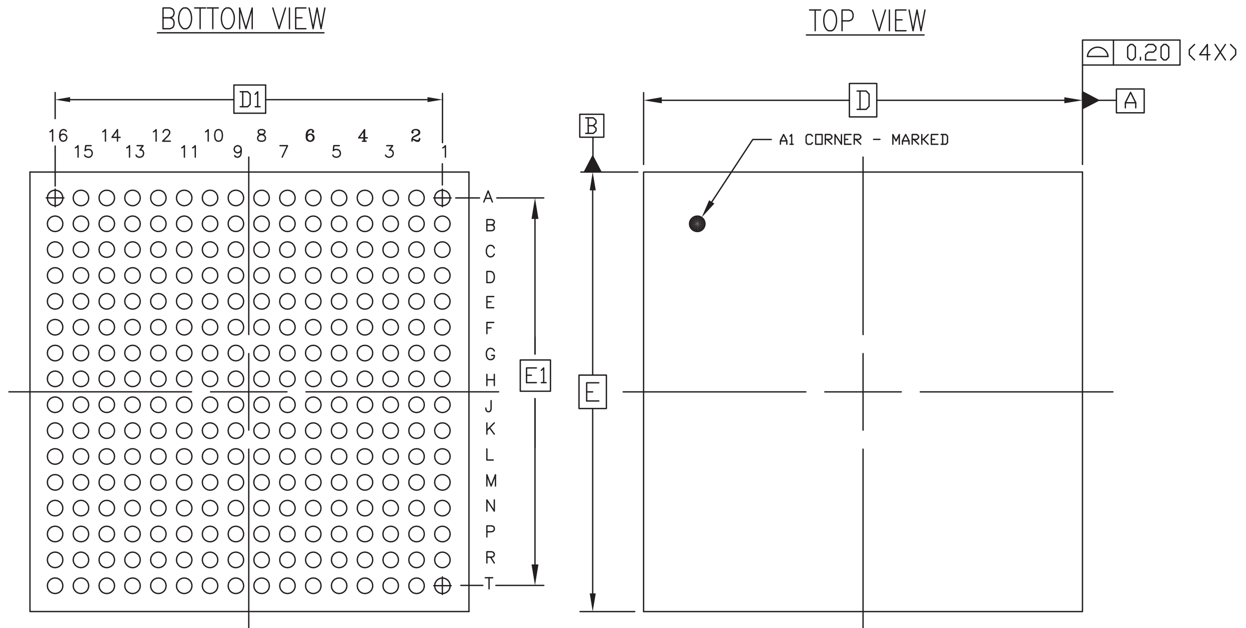
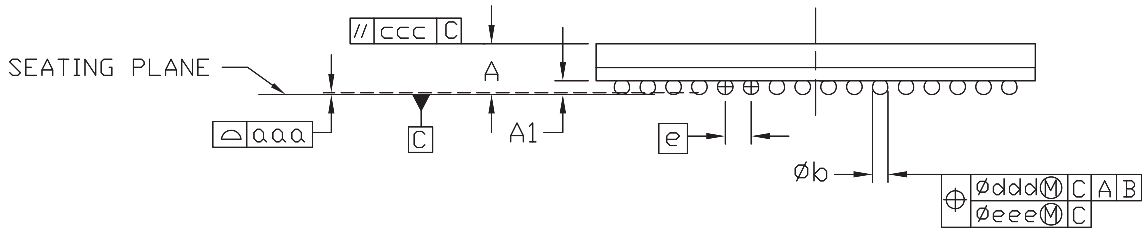
256 Ball Fine-Pitch Thin BGA (FT256/FTG256) Package





SYMBOL	MILLIMETERS		
	MIN.	NOM.	MAX.
A	—	1.40	1.55
A_1	0.30	0.40	0.50
D/E	17.00 BSC		
D_1/E_1	15.00 REF		
e	1.00 BSC		
Øb	0.40	0.50	0.60
aaa	—	—	0.20
ccc	—	—	0.15
ddd	—	—	0.25
eee	—	—	0.10
M	16		

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M–1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034 AAF-1 EXCEPT FOR THE SOLDER BALL SIZE.

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/23/05	1.2.1	Update.
10/05/07	1.3	Changed the A1 minimum dimension to 0.30 mm.
03/23/11	1.4	Changed the FTG256 solder ball description.

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